

MATERIAL DECLARATION SHEET



Material Number	CDSOT236-0502			
Product Line	Semiconductor Products			
Compliance Date	2013/8/6			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.000500	Silicon	7440-21-3	100.00%	3.125%	3.125%
2	Lead frame	Copper Alloy	0.003335	Copper	7440-50-8	95.295%	20.845%	21.875%
			0.000088	Iron	7439-89-6	2.50%	0.547%	
			0.000004	phosphorous	7723-14-0	0.10%	0.022%	
			0.000004	Zinc	7440-66-6	0.10%	0.022%	
			0.000070	Silver	7440-22-4	2%	0.438%	
			0.0000002	Lead	7439-92-1	0.005%	0.001%	
3	Epoxy	Polymer	0.000280	Acrylic Resin	Trade Secret	28.00%	1.748%	6.250%
			0.000150	Polybutadiene derivative	Trade Secret	15.00%	0.938%	
			0.000030	Butadiene copolymer	Trade Secret	3.00%	0.188%	
			0.000250	Acrylate	Trade Secret	25.00%	1.561%	
			0.000050	Epoxy resin	Trade Secret	5.00%	0.313%	
			0.000050	Peroxide	Trade Secret	5.00%	0.313%	

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			0.000050	Additive	Trade Secret	5.00%	0.313%	
			0.000070	Silica	68611--44--9	7.00%	0.438%	
			0.000070	Boron compound	Trade Secret	7.00%	0.438%	
4	Cu Wire	Noble metal	0.000975	Copper	7440-50-8	97.50%	6.094%	6.250%
			0.000025	Palladium	7440-05-3	2.50%	0.156%	
5	Mold Compound	Polymer	0.000450	Solid Epoxy Resin	Trade Secret	5.00%	2.813%	56.250%
			0.000450	Phenol Resin	Trade Secret	5.00%	2.813%	
			0.007650	Fused Silica	60676-86-0	85.00%	47.812%	
			0.000045	Crystalline Silica	14808-60-7	0.50%	0.281%	
			0.000045	Carbon Black	01333-86-4	0.50%	0.281%	
			0.000360	Metal Hydroxide	Trade Secret	4.00%	2.250%	
6	Plating	Plating	0.001000	Tin	7440-31-5	99.99%	6.249%	6.250%
			0.0000001	Others		0.01%	0.001%	
Total weight			0.016 g					

This Document was updated on: 2013/8/6

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.